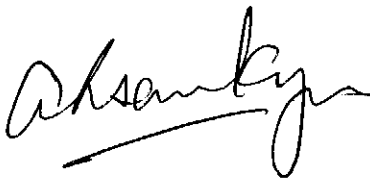


July 29, 2005

Dear Coustomer,

As of October 1st, 2005, unless specifically agreed otherwise, all ISSI lead-free components will use 100% matte tin (Sn) as the soldering plating material, except for parts with BGA packaging. Lead-free BGA components use a solder ball composition of 95.5% Sn, 4% Ag, 0.5% Cu.

The part numbers of lead-free components contain the character "L" immediately following the package character to distinguish them from non-lead-free components. For example, IS61C1024AL-12TLI is lead-free TSOP. In contrast, IS61C1024AL-12TI is not lead-free. Lead-free components from ISSI are 100% ROHS compliant.



Ah-San Kyu
Sr. Director
Operation Department
ISSI